

GSM2309KP

30V P-Channel Enhancement Mode MOSFET

Product Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

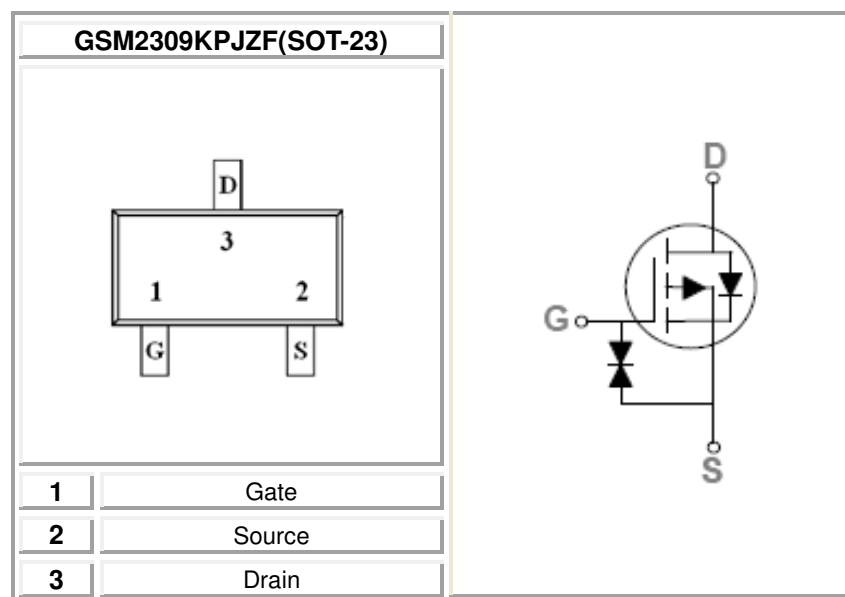
Features

- -30V, -3.8A, $R_{DS(ON)}=75m\Omega@V_{GS}=-10V$
- Fast switching
- Suit for -4.5V Gate Drive Applications
- G-S ESD Protection Diode Embedded
- Green Device Available
- SOT-23 package design

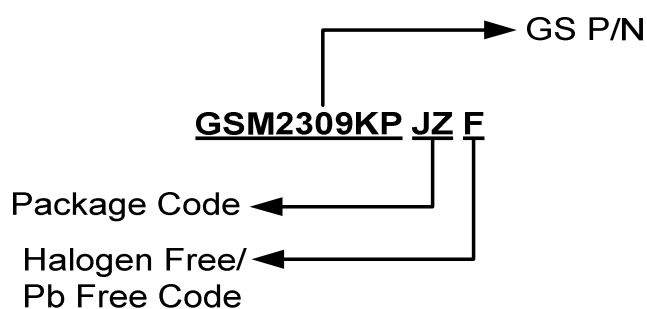
Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

Packages & Pin Assignments

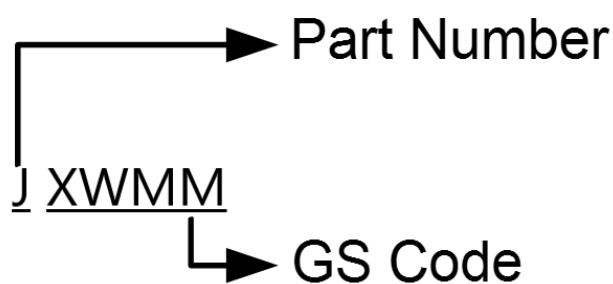


Ordering Information



Part Number	Package	Quantity Reel
GSM2309KPJZF	SOT-23	3000 PCS

Marking Information



Absolute Maximum Ratings

(T_A=25°C unless otherwise noted)

Symbol	Parameter	Typical	Unit	
V _{DS}	Drain-Source Voltage	-30	V	
V _{GS}	Gate-Source Voltage	±25	V	
I _D	Continuous Drain Current (T _J =150°C)	T _A =25°C	-3.8	A
		T _A =70°C	-3.0	
I _{DM}	Pulsed Drain Current ¹	-15.2	A	
P _D	Power Dissipation	1.56	W	
	Power Dissipation (Derate above 25°C)	0.012	W/°C	
T _J	Operating Junction Temperature Range	-55 to +150	°C	
T _{STG}	Storage Temperature Range	-55 to +150	°C	
R _{θJA}	Thermal Resistance-Junction to Ambient	80	°C/W	

Electrical Characteristics

($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ	Max.	Unit
Static						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.2	-1.6	-2.2	
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient	$V_{DS}=V_{GS}, I_D=-250\mu A$		4		$\text{mV}/^{\circ}\text{C}$
I_{GSS}	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 25V$			± 20	μA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30V, V_{GS}=0V$			-1	μA
		$V_{DS}=-24V, V_{GS}=0V, T_J=125^{\circ}\text{C}$			-10	
I_S	Continuous Source Current	$V_G=V_D=0V,$ Force Current			-3.8	A
I_{SM}	Pulsed Source Current				-15.2	
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=-10V, I_D=-3A$		64	75	$\text{m}\Omega$
		$V_{GS}=-4.5V, I_D=-2A$		105	130	
g_{fs}	Forward Transconductance	$V_{DS}=-10V, I_D=-3A$		3.5		S
V_{SD}	Diode Forward Voltage	$I_S=-1A, V_{GS}=0V$			-1	V
Dynamic						
C_{iss}	Input Capacitance	$V_{DS}=-15V,$ $V_{GS}=0V, f=1\text{MHz}$		460	665	pF
C_{oss}	Output Capacitance			45	65	
C_{riss}	Reverse Transfer Capacitance			30	45	
Q_g	Total Gate Charge ^{2,3}	$V_{DS}=-15V,$ $V_{GS}=-4.5V, I_D=-3A$		4.2	6	nC
Q_{gs}	Gate-Source Charge ^{2,3}			1.9	2.5	
Q_{gd}	Gate-Drain Charge ^{2,3}			1.4	2	
$t_{d(on)}$	Turn-On Time ^{2,3}	$V_{DD}=-15V, I_D=-1A,$ $V_{GS}=-10V, R_G=6\Omega$		2.8	5	ns
T_r				8.7	17	
$t_{d(off)}$	Turn-Off Time ^{2,3}			21.4	41	
T_f				5.7	11	

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

Typical Performance Characteristics

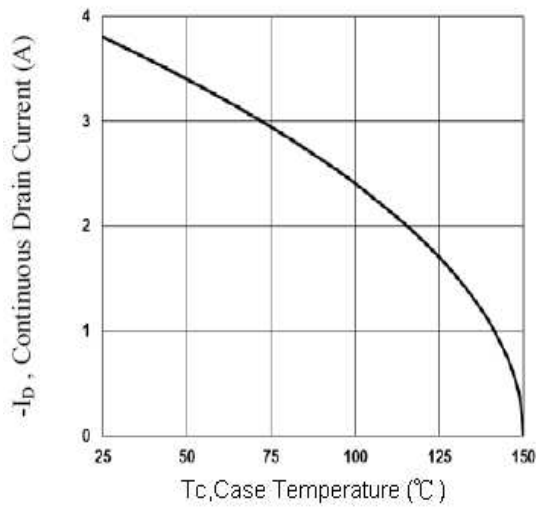


Fig.1 Continuous Drain Current vs. T_c

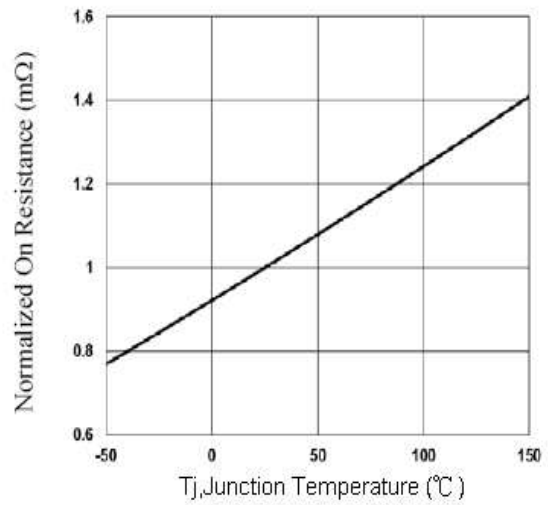


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

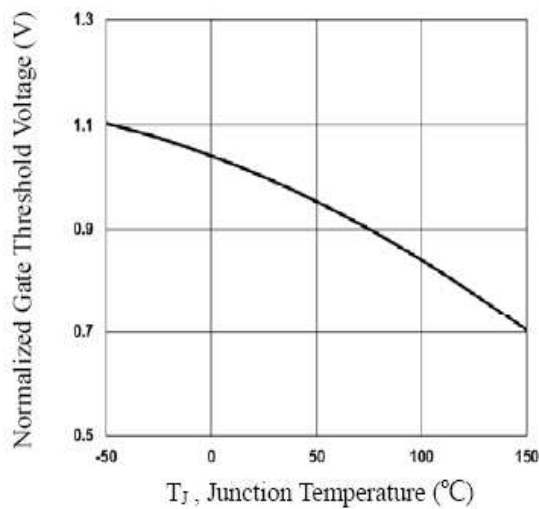


Fig.3 Normalized V_{th} vs. T_j

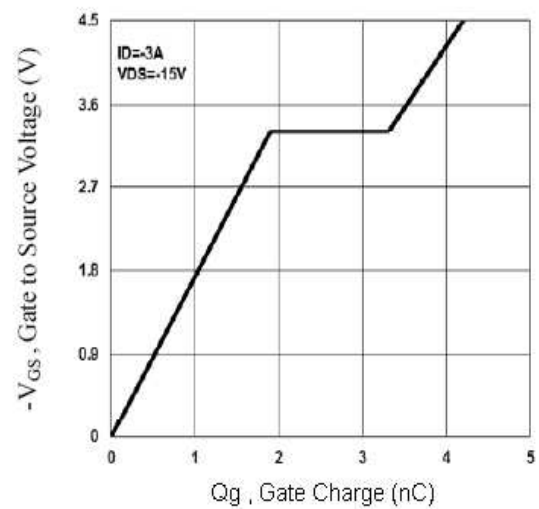


Fig.4 Gate Charge Waveform

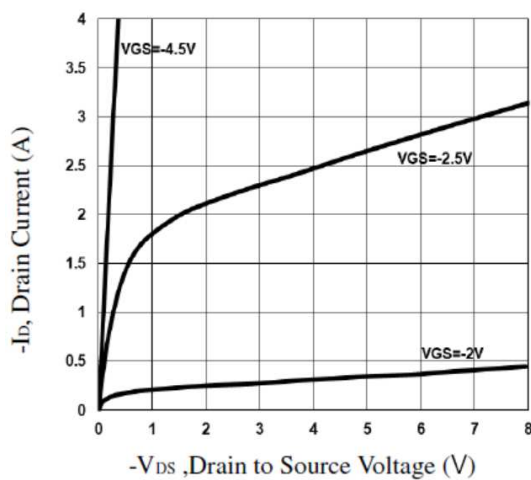


Fig.5 Typical Output Characteristics

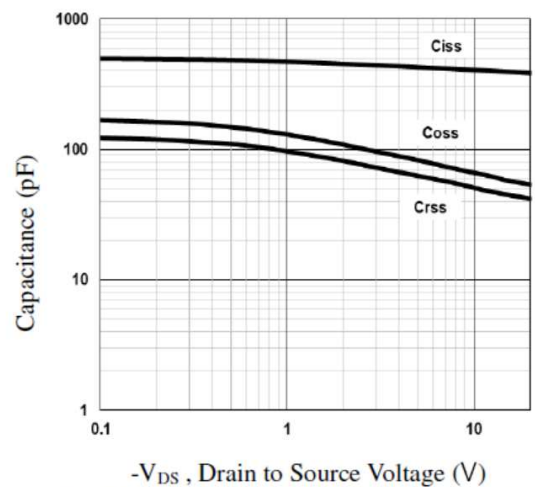


Fig.6 Capacitance Characteristics

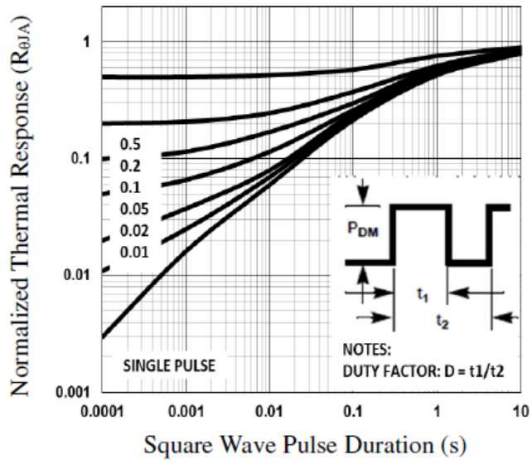


Fig.7 Normalized Transient Impedance

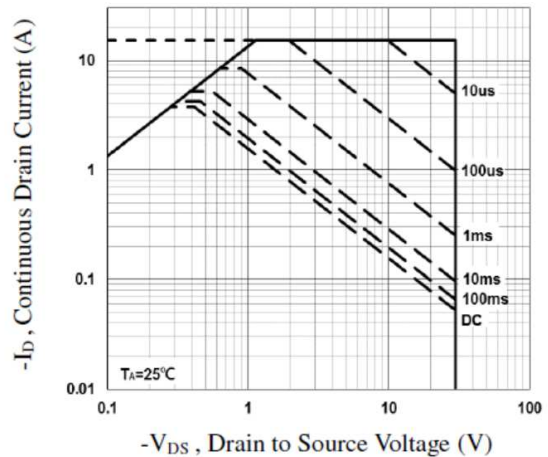
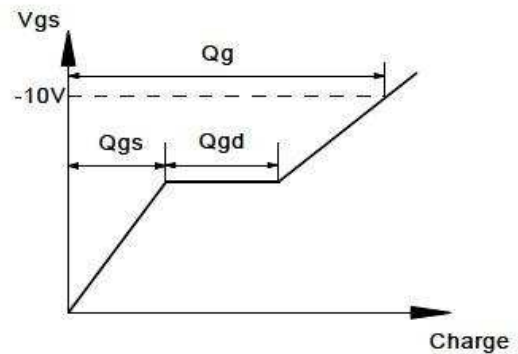
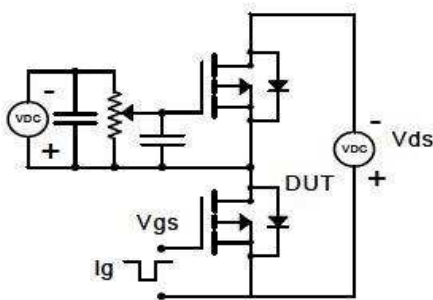
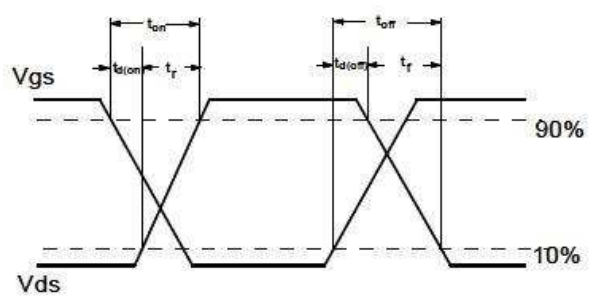
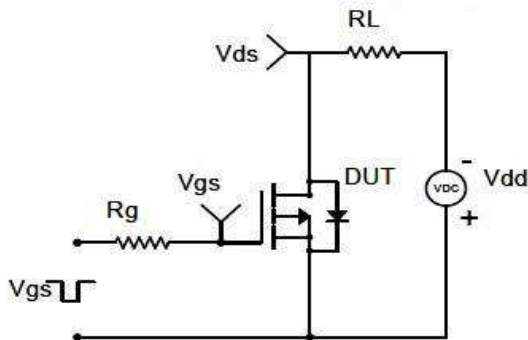


Fig.8 Maximum Safe Operation Area

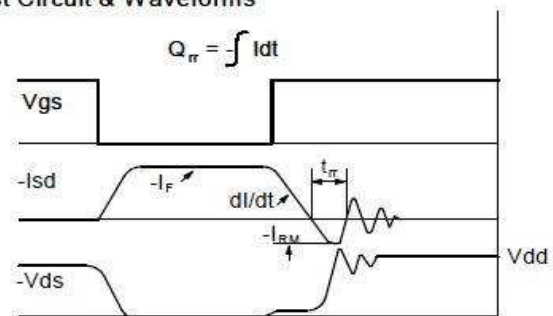
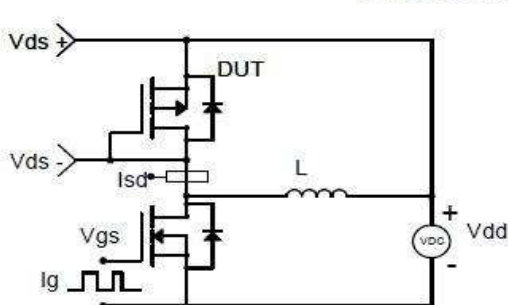
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

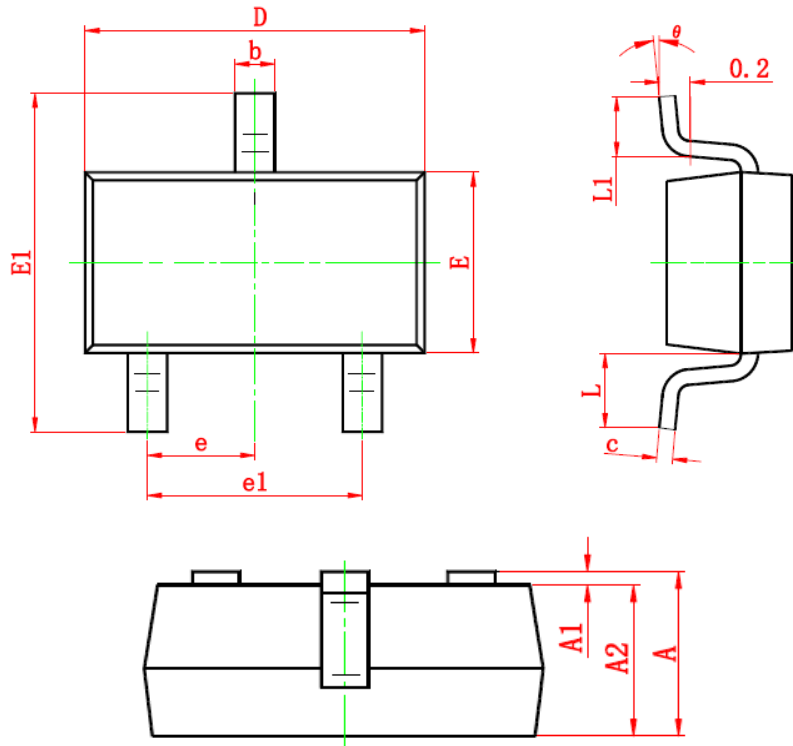


Diode Recovery Test Circuit & Waveforms



Package Dimension

SOT-23









Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.900	1.000	0.035	0.039
A1	0.000	0.100	0.000	0.004
A2	-	0.900	-	0.035
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	6°

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